

Filename: PMP8586 REV\_A\_bom.xls

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## PMP8586 REV\_A BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C3	SHORT	N/A	N/A	SHORT	N/A
1	C4	470pF	Capacitor, Ceramic, 250V, C0G, 20%	0603	STD	STD
1	C7	470uF	Capacitor, Aluminum Electrolytic, 35V, 10x16mm	0.315 inch	EKZM350ESS471MJ16S	Nippon Chemi-Con
1	C8	33uF	Capacitor, Electrolytic PTH, 450V, 16x20mm	0.571 inch	EKXJ451ESS330ML20S	Nippon Chemi-Con
1	C13	2.2nF	Capacitor, Safety Y1/X1, Ceramic Disk, 250V	0.394 X 0.315 inch Max.	ECKANA222MB	Panasonic
1	C14	0.47uF	Capacitor, Ceramic, 6.3V, X7R, 10%	0603	Std	Std
1	C15	220pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C16	1uF	Capacitor, Ceramic, 16V, X7R, 20%	0603	C1608X7R1C105M	TDK
1	C17	4700pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C18	470pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C19	5600pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C20	4.7uF	Capacitor, Ceramic Chip, 25V, X7R, ±10%	1206	C3216X7R1E475K	TDK
2	C2 C12	0.1 uF	Capacitor, Leaded, 305 VAC, X2		B32921A2104M289	EPCOS
3	C5-6 C11	10uF	Capacitor, Ceramic, 25V, X5R, 20%	1210	C3225X5R1E106M	TDK
1	D2	STPS3150U	Diode, Schottky, 3A, 150V	SMB	STPS3150U	ST
1	D3	US1J	Diode, Rectifier, 1A, 600V	SMA	US1J	Diodes
1	D4	MB8S	Diode, Bridge Rectifier, 0.5A, 800V	SO-4	MB8S	Fairchild
1	D6	BAS19	Diode, Switching, 120V, 200mA	SOT23	BAS19LT1	On Semiconductor
1	D8	BAS16	Diode, Switching, 75V, 200mA	SOT23	BAS16LT1	On Semiconductor
1	J5	PEC12SAAN	Header, Male 12-pin, 100mil spacing,	0.100 inch x 12	PEC12SAAN	Sullins
2	J3-4	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins
1	L3	2.2uH	Inductor, SMT, 2.3A, 70-milliohm	0.26x0.09 inch	DO1608-222ML	Coilcraft
4	L2 L5-7	1mH	Inductor, Filter Chocke, 0.42-A, 2.5-Ohm	0.350 x 0.300 inch	744743102	Wuerth
4	MH1-4		Through Hole for Screw #6	# 6-32	THT Screw Hole	
1	Q1	FQD2N60C	MOSFET, Nch, 600V, 1.9-A, 4.7-Ohm	DPAK	FQD2N60C	Fairchild
1	R5	47	Resistor, Chip 1/4 watt, ± 5%	1206	Std	STD
1	R6	120k	Resistor, Chip, 1/4W, 5%	1210	Std	Std
1	R11	4.7	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R20	10	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R21	20 Ohms	Thermistor, NTC, 20 Ohms	0.394 inch.	B57236S200M	Epcos
1	R26	275V	Varistor, 275V	0.472 x 0.213 inch	SIOV-S10K275E2	Epcos
1	R27	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R28	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R29	42.2k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R30	25.5k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R36	150k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R37	475	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R38	0.68	Resistor, Chip, 1/10W, 1%	0805	Std	Std

1	R39	6.81k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R40	49.9k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R17 R14	1M	Resistor, Chip, 1/4W, 5%	1210	Std	Std
3	R31-33	4.99k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
4	R7 R19 R23 R34	10k	Resistor, Chip, 1/4W, 5%	1210	Std	Std
1	T1	750811434	Transformer,	20.3x24.38 mm	750811434	WE
1	U1	LM5021-2	IC, AC-DC Current Mode PWM Controller	MSOP	LM5021MMX-2	TI
1	U2	TCMT1107	IC, Photocoupler	MF4	TCMT1107	Vishay
1	U3	TL431AIDBZ	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431AIDBZ	TI

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
  2. These assemblies must be clean and free from flux and all contaminants.  
Use of no clean flux is not acceptable.
  3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
  4. Ref designators marked with an asterisk (\*\*\*) cannot be substituted.  
All other components can be substituted with equivalent MFG's components.

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